## 2SK1307

## Silicon N-Channel MOS FET

# **HITACHI**

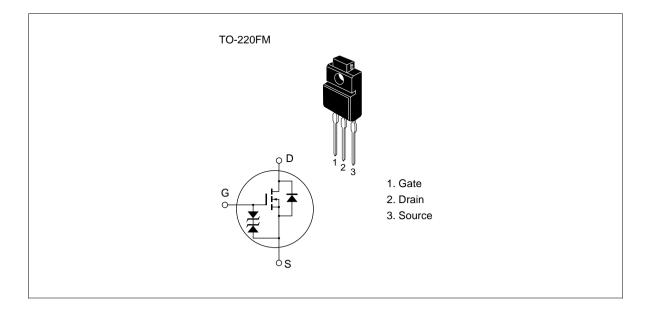
### **Application**

High speed power switching

#### **Features**

- Low on-resistance
- High speed switching
- 4 V gate drive device
  - Can be driven from 5 V source
- Suitable for motor drive, DC-DC converter, power switch and solenoid drive

#### **Outline**





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## **Absolute Maximum Ratings** ( $Ta = 25^{\circ}C$ )

Item	Symbol	Ratings	Unit
Drain to source voltage	V <sub>DSS</sub>	100	V
Gate to source voltage	$V_{\sf GSS}$	±20	V
Drain current	I <sub>D</sub>	20	A
Drain peak current	I <sub>D(pulse)</sub> *1	80	A
Body to drain diode reverse drain current	I <sub>DR</sub>	20	A
Channel dissipation	Pch*2	35	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW  $\leq$  10  $\mu$ s, duty cycle  $\leq$  1%

2. Value at  $T_c = 25^{\circ}C$ 

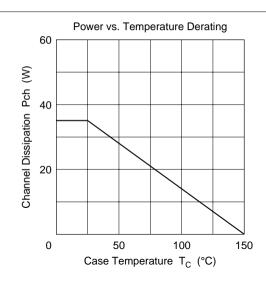
## **Electrical Characteristics** ( $Ta = 25^{\circ}C$ )

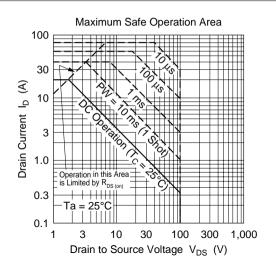
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	100	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±20	_	_	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I <sub>GSS</sub>	_	_	±10	μΑ	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I <sub>DSS</sub>	_	_	250	μΑ	$V_{DS} = 80 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	1.0	_	2.0	V	$I_{D} = 1 \text{ mA}, V_{DS} = 10 \text{ V}$
Static drain to source on state resistance	R <sub>DS(on)</sub>	_	0.065	0.085	Ω	$I_D = 10 \text{ A}, V_{GS} = 10 \text{ V}^{*1}$
		_	0.085	0.12	Ω	$I_D = 10 \text{ A}, V_{GS} = 4 \text{ V}^{*1}$
Forward transfer admittance	yfs	10	16	_	S	I <sub>D</sub> = 10 A, V <sub>DS</sub> = 10 V *1
Input capacitance	Ciss	_	1300	_	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$
Output capacitance	Coss	_	540	_	pF	f = 1 MHz
Reverse transfer capacitance	Crss	_	160	_	pF	
Turn-on delay time	t <sub>d(on)</sub>	_	12	_	ns	$I_D = 10 \text{ A}, V_{GS} = 10 \text{ V},$
Rise time	t <sub>r</sub>	_	100	_	ns	$R_L = 3 \Omega$
Turn-off delay time	t <sub>d(off)</sub>	_	300	_	ns	<del></del>
Fall time	t <sub>f</sub>	_	150	_	ns	<del></del>
Body to drain diode forward voltage	$V_{DF}$	_	1.3	_	V	I <sub>F</sub> = 20 A, V <sub>GS</sub> = 0
Body to drain diode reverse recovery time	t <sub>rr</sub>		300	_	ns	$I_F = 20 \text{ A}, V_{GS} = 0,$ $di_F/dt = 50 \text{ A}/\mu\text{s}$

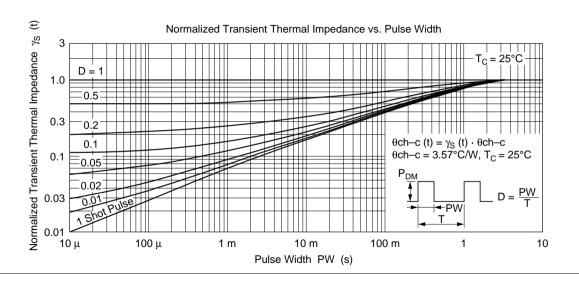
Note: 1. Pulse test

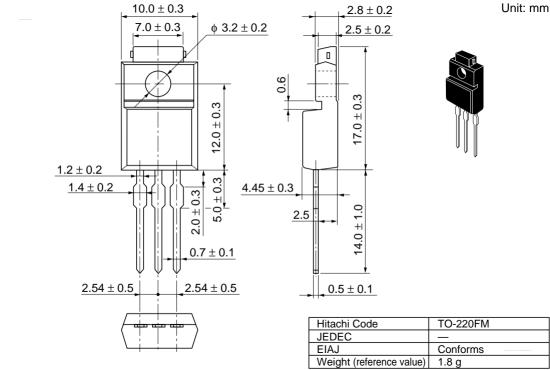
See characteristic curves of 2SK1302.

## 2SK1307









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